

75V N-Channel MOSFET

Features

- 80A, 75v, RDS(on)=11mΩ@VGS=10V
- Gate charge (Typical 64nC)
- High ruggedness
- Fast switching
- 100% Avalanche Tested
- Improved dv/dt capability

Application

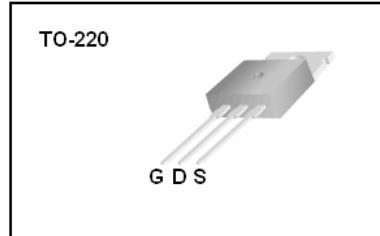
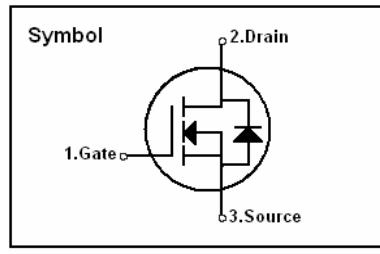
- DC Motor Control
- Solenoid and Relay Drivers
- DC-DC Converters
- Automotive Environment

Advantage

- Easy to Mount
- Space Savings
- High Power Density

Absolute Maximum Ratings

Symbol	Parameter	Value	Units
VDSS	Drain to Source Voltage	75	V
ID	Continuous Drain Current(@TC = 25°C)	80	A
	Continuous Drain Current(@TC = 100°C)	53	A
IDM	Drain Current Pulsed (Note 1)	320	A
VGS	Gate to Source Voltage	±20	V
EAS	Single Pulsed Avalanche Energy (Note 2)	700	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	12	V/ns
PD	Total Power Dissipation(@TC = 25 °C)	300	W
TSTG, TJ	Operating Junction Temperature & Storage Temperature	-55 ~ 175	°C
TL	Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds.	300	°C



Thermal Characteristics

Symbol	Parameter	Value	Units
R _{θJC}	Thermal Resistance, Junction-to-Case	0.5	°C/W
R _{θJA}	Thermal Resistance, Junction	62.5	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

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Electrical Characteristics (TC = 25 °C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250uA	75	83	-	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} = 75V, V _{GS} = 0V	-	-	1	uA
		V _{DS} = 60V, T _C = 125 °C	-	-	10	uA
I _{GSS}	Gate-Source Leakage, Forward	V _{GS} = 20V, V _{DS} = 0V	-	-	100	nA
	Gate-source Leakage, Reverse	V _{GS} = -20V, V _{DS} = 0V	-	-	-100	nA
On Characteristics						
V _{G(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250uA	2.0	2.5	4.0	V
R _{D(ON)}	Static Drain-Source On-state Resistance	V _{GS} = 10 V, I _D = 40A	-	9.4	11	mΩ
g _F	Forward Transconductance	V _{DS} = 15 V, I _D = 40A	-	80	-	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0 V, V _{DS} = 25V, f = 1MHz	-	2950	-	pF
C _{oss}	Output Capacitance		-	768	-	
C _{rss}	Reverse Transfer Capacitance		-	8	-	
Dynamic Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} = 37.5V, I _D = 45A, V _{GS} = 10V, R _G = 4.7Ω (Note 4, 5)	-	34	-	ns
t _r	Rise Time		-	3	-	
t _{d(off)}	Turn-off Delay Time		-	62	-	
t _f	Fall Time		-	13	-	
Q _g	Total Gate Charge	V _{DS} = 60V, V _{GS} = 10V, I _D = 75A (Note 4, 5)	-	64	-	nC
Q _{gs}	Gate-Source Charge		-	20	-	
Q _{gd}	Gate-Drain Charge(Miller Charge)		-	14	-	

Source-Drain Diode Ratings and Characteristics

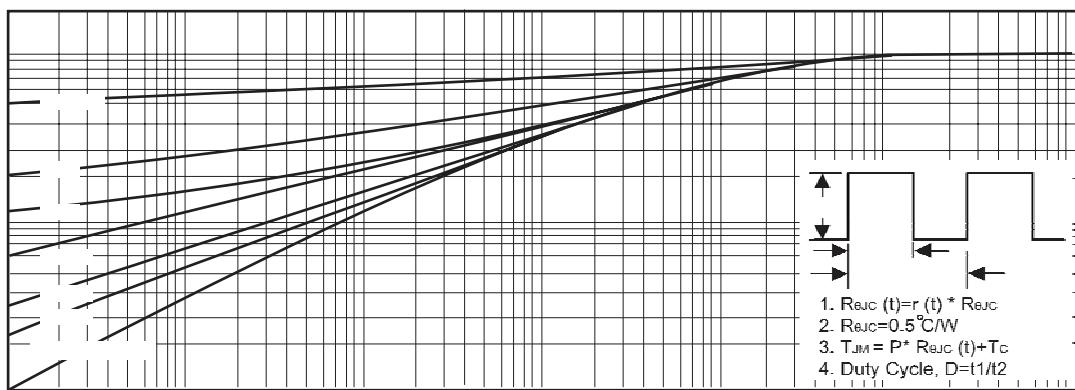
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit.
I _S	Continuous Source Current	Integral Reverse p-n Junction	-	-	80	A
I _{SM}	Pulsed Source Current	Diode in the MOSFET	-	-	320	
V _{SD}	Diode Forward Voltage	I _S =80A, V _{GS} =0V	-	0.98	1.4	V
t _{rr}	Reverse Recovery Time	I _S =80A, V _{GS} =0V,dI _F /dt=100A/us	-	130	-	ns
Q _{rr}	Reverse Recovery Charge	I _S =80A, V _{GS} =0V,dI _F /dt=100A/us	-	0.6	-	uC

NOTES

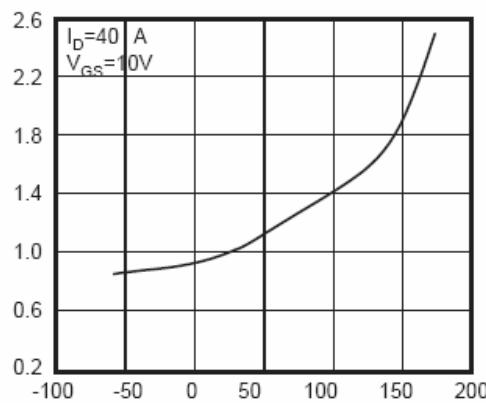
- a. Repetitive Rating : Pulse width limited by maximum junction temperature.
- b. Pulse Test : Pulse Width < 300μs, Duty Cycle < 2%.
- c. Guaranteed by design, not subject to production testing.
- d. L=1mH, V_{DD} = 38V, I_D=37.5A, R_G = 25Ω, Starting T_J = 25 °C



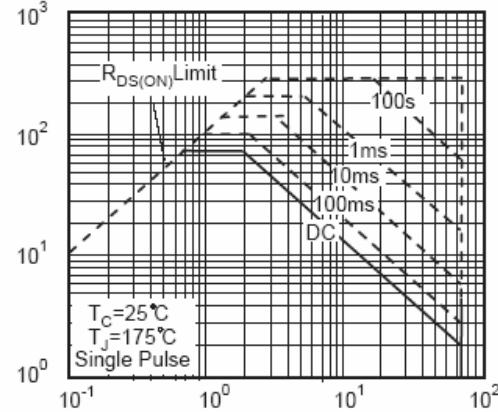
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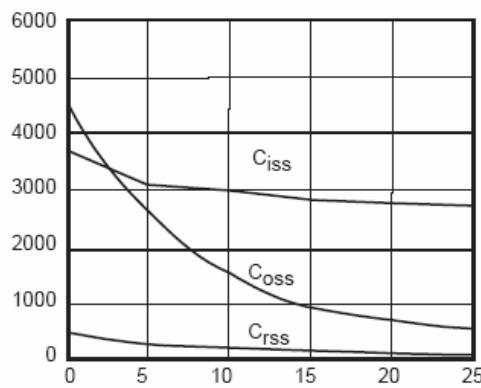
Square Pulse Duration (sec)
Figure 1. Normalized Effective Transient Thermal Impedance With Pulse Duration



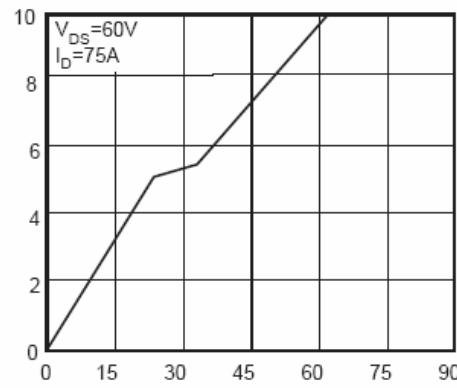
T_J, Junction Temperature(C)
Figure 2. Normalized On-Resistance Variation with Temperature



V_{DS}, Drain-Source Voltage (V)
Figure 3. Maximum Safe Operating Area



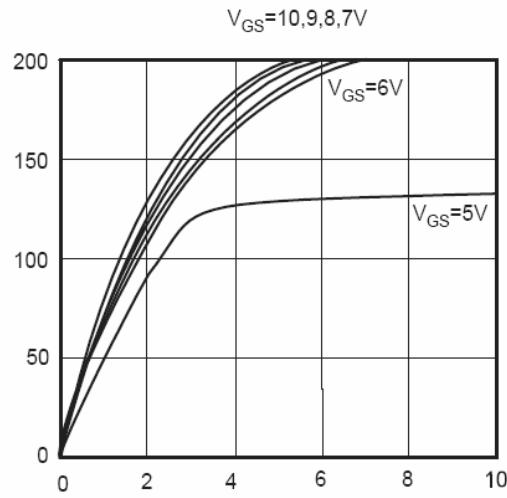
V_{DS}, Drain-to-Source Voltage (V)
Figure 4. Capacitance Characteristics



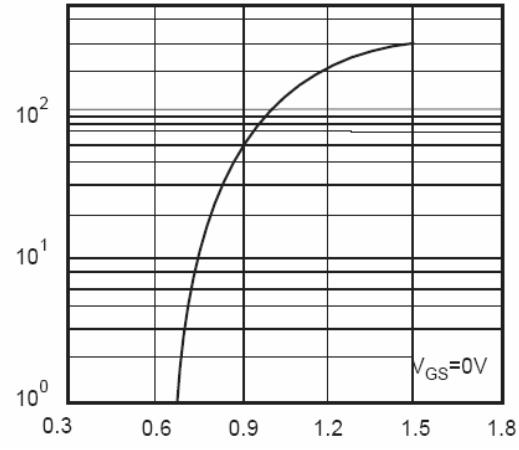
Q_g, Total Gate Charge (nC)
Figure 5. Gate Charge Characteristics



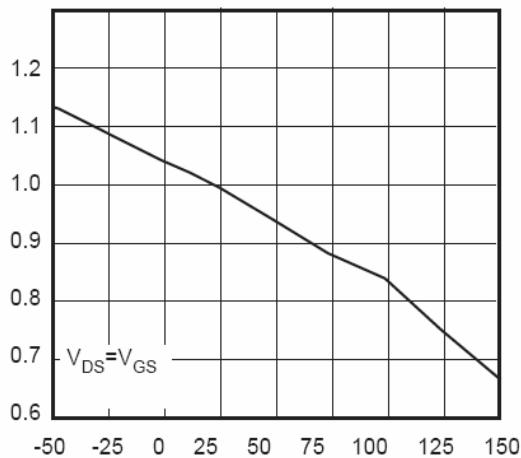
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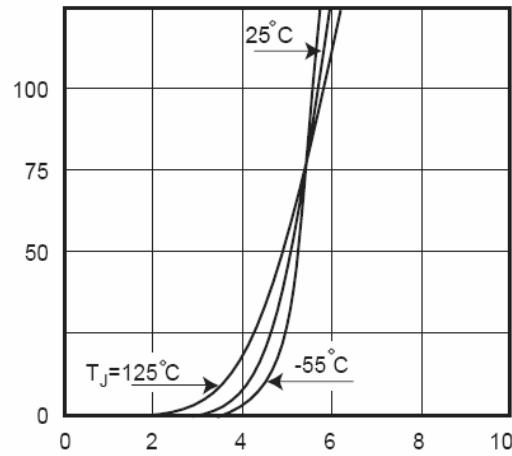
V_{DS}, Drain-to-Source Voltage (V)
Figure 6. On-State Characteristics



V_{SD}, Body Diode Forward Voltage (V)
Figure 7. Body Diode Forward Voltage Variation with Source Current



T_J, Junction Temperature (C)
Figure 8. Gate Threshold Variation with Temperature



V_{GS}, Gate-to-Source Voltage (V)
Figure 9. Transfer Characteristics



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Fig. 12. Gate Charge Test Circuit & Waveforms

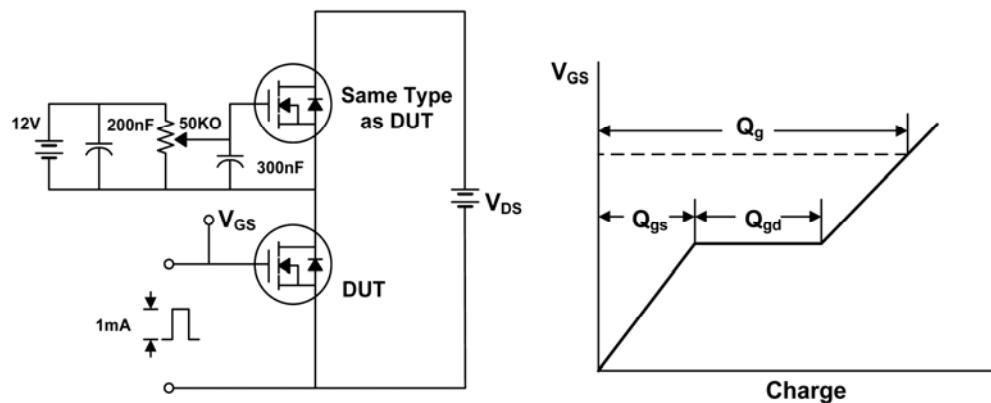


Fig 13. Switching Time Test Circuit & Waveforms

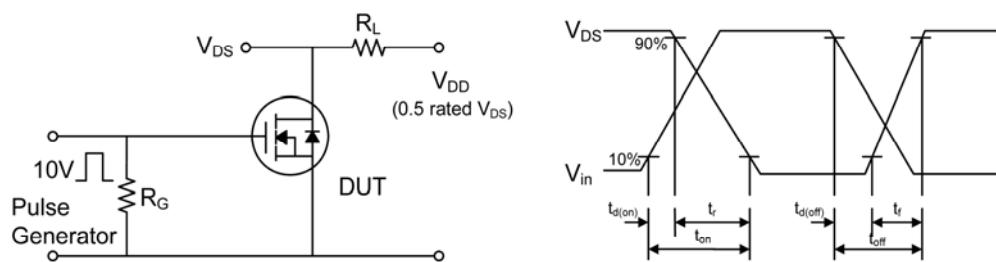
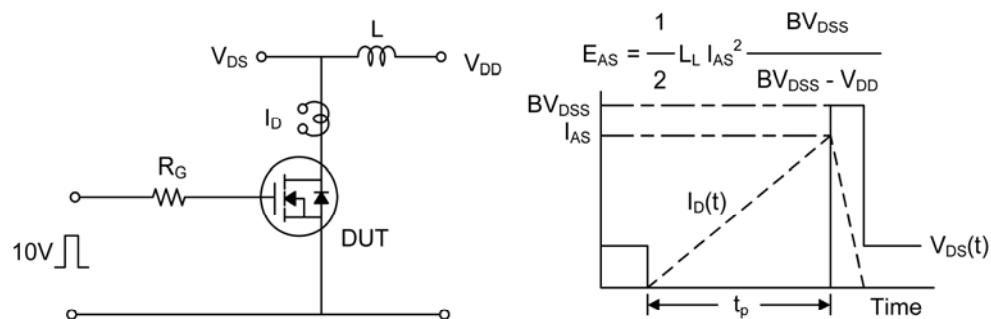


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig. 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

